

William C. Paltz

Associate

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William (Will) Paltz is a registered patent attorney who provides a broad range of intellectual property services. Will counsels clients with respect to intellectual property matters, with an emphasis on patents relating to electronics and software. A significant component of Will's practice includes addressing complex patent-eligibility issues.

As a patent counselor, Will helps clients identify and implement the appropriate strategy to protect their innovations; navigate and alleviate patent-eligibility issues; and identify and mitigate IP infringement risks by providing freedom-to-operate and clearance opinions. Will regularly prepares and prosecutes domestic and international patent applications across a broad spectrum of technology areas, including:

- Software and business methods
- Medical Devices, Health Technology, and Digital Health
- Data science and predictive analytics
- Advanced computer modeling
- Artificial intelligence/machine learning, including generative AI
- Advertisements and marketing
- Financial technologies (Fintech)
- Semiconductor technologies and memory solutions
- Cybersecurity

Before joining Foley, Will served as a control hardware engineer intern at Rockwell Automation, where he was responsible for field-programmable gate array (FPGA) design and development activities. He also served as a software and firmware quality engineer intern, wherein he performed backend development and software and firmware development lifecycle optimization. During law school, Will served as the president of the Intellectual Property Organization (IPO).

Affiliations

- Member, Institute of Electrical and Electronics Engineers (IEEE)

Sectors

- [Artificial Intelligence](#)
- [Blockchain & Digital Assets](#)
- [Innovative Technology](#)
- [Non-Fungible Tokens \(NFTs\)](#)

Practice Areas

- [Intellectual Property](#)
- [Mechanical & Electromechanical Technologies](#)

Education

- Southern Methodist University – Dedman School of Law (J.D., *cum laude*, 2023)
- University of Wisconsin, Milwaukee (B.S., summa cum laude, 2019)
 - Computer engineering

Admissions

- Texas
- U.S. Patent and Trademark Office